

Claims

1. Casing (10) for transport of a toner mixture on its outer surface in a development device,
5 whereby the wall of the casing (10) is essentially comprised of an electrically-conductive material and the outer surface of the casing (10) bears a layer made from nickel-copper.
- 10 2. Casing according to claim 1, in which the layer is generated via chemical deposition.
3. Casing according to claim 2, in which a chemical nickel-copper-phosphor deposition occurs as a chemical deposition process.
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4. Casing according to any of the preceding claims, in which the layer comprises 1 to 2 % copper and 8 to 10 % phosphor.
5. Casing according to any of the preceding claims, in which the thickness of
20 the layer lies in the range of 15 – 25 μm .
6. Casing according to any of the preceding claims, in which the wall of the casing (10) is essentially comprised of aluminum.
- 25 7. Casing according to any of the preceding claims, in which the toner mixture is a two-component mixture which comprises ferromagnetic carrier particles and toner particles.
8. Method for production of a casing (10) according to any of the preceding
30 claims,

in which a metal casing is chemically pre-treated,

and a chemical deposition subsequently occurs in which a nickel-copper-phosphor layer is generated.

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9. Method according to claim 8, in which a layer is generated in the chemical deposition that comprises 1 to 2 % copper, 8 to 10 % phosphor and the remainder is essentially nickel.

- 10 10. Method according to any of the preceding claims, in which an aluminum casing on which a conductive layer is applied in a zincate etching after the chemical pre-treating is used as a casing,

a chemical pre-nickeling occurs thereupon,

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and the chemical nickel-copper-phosphor deposition subsequently occurs.

11. Method according to any of the preceding claims, in which a chemical bath which comprises:

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nickel sulfate 30 g/l, copper sulfate 0.6 to 1.5 g/l, sodium hyperphosphite 15 g/l, sodium citrate 50 g/l, ammonium chloride 40 g/l

is used for chemical nickel-copper-phosphor deposition.

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12. Method according to claim 11, in which the bath has a pH value of 9.0 and a temperature of 75°C.